

Amendments to the Claims:

The **Listing of Claims** below replaces all prior versions, and listings, of claims in the Application.

Listing of Claims:

1. (previously presented) A circuitized substrate comprising:
 - first and second dielectric layers, each of said first and second dielectric layers having first and second opposing sides;
 - a substantially solid conductive ground plane located between said first opposing side of said first dielectric layer and said first opposing side of said second dielectric layer;
 - a first conductive signal line located on said second opposing side of said first dielectric layer and a second conductive line located on said second opposing side of said second dielectric layer;
 - first and second conductive ground lines located on said second opposing side of said first dielectric layer on opposite sides of said first conductive signal line and electrically coupled to said substantially solid conductive ground plane located on said first opposing side of said dielectric layer; and
 - a first conductive thru-hole extending through said substantially solid conductive ground plane and electrically coupling said first conductive signal line to said second conductive signal line, said first and second conductive ground lines and said substantially conductive ground plane providing shielding for said at least

one conductive signal line during the passage of electrical current through said signal line.

2. (previously presented) The circuitized substrate of claim 1 wherein said first and second dielectric layers are each selected from the group consisting of fiberglass-reinforced polymer resin, Teflon and Driclad and combinations thereof.
3. (previously presented) The circuitized substrate of claim 1 wherein said substantially solid conductive ground plane is comprised of copper.
4. (previously presented) The circuitized substrate of claim 1 wherein each of said first and second conductive signal lines is comprised of copper.
5. (previously presented) The circuitized substrate of claim 1 wherein said first and second conductive ground lines are each comprised of copper.
6. (previously presented) The circuitized substrate of claim 1 further including second and third conductive thru-holes, said second and third conductive thru-holes electrically coupling said first and second conductive ground lines to said substantially solid conductive ground plane, respectively.
- 7 and 8 (cancelled)
9. (original) The circuitized substrate of claim 1 further including additional dielectric and conductive layers as part thereof.

10. (original) The circuitized substrate of claim 9 further including first and second pluralities of external conductive pads located on opposite sides of said circuitized substrate for electrically coupling said circuitized substrate to external electrical components.
11. (original) The invention of claim 10 wherein said circuitized substrate is a chip carrier.
12. (original) The invention of claim 10 wherein said circuitized substrate is a printed circuit board.
13. (previously presented) The circuitized substrate of claim 1 further including a third conductive signal line positioned on said second opposing side of said first dielectric layer adjacent said first conductive signal line, said first and second conductive ground lines and said substantially solid conductive ground plane also providing shielding for said third conductive signal line during the passage of electrical current through said third conductive signal line.
14. (previously presented) The circuitized substrate of claim 13 further including a conductive ground line positioned on said second opposing side of said first dielectric layer substantially between said first and third conductive signal lines, said conductive ground line also providing shielding for said first and third conductive signal lines during the passage of electrical current through said first and third conductive signal lines.
15. (previously presented) The circuitized substrate of claim 1 further including third and fourth dielectric layers positioned on said first and second dielectric layers, respectively, and second and third substantially solid conductive ground planes positioned on said third and fourth dielectric layers, respectively, said second and

third substantially solid conductive ground planes also providing shielding for said at least one conductive signal line during the passage of electrical current through said signal line.

16 – 21 (cancelled).

22. (previously presented) An electrical assembly comprising:

an electrical component; and

a printed circuit board including a circuitized substrate having first and second dielectric layers, each of said first and second dielectric layers having first and second opposing sides, a substantially solid conductive ground plane located between said first opposing side of said first dielectric layer and said first opposing side of said second dielectric layer, a first conductive signal line located on said second opposing side of said first dielectric layer and a second conductive line located on said second opposing side of said second dielectric layer; first and second conductive ground lines located on said second opposing side of said first dielectric layer on opposite sides of said first conductive signal line and electrically coupled to said substantially solid conductive ground plane located on said first opposing side of said dielectric layer, and a first conductive thru-hole extending through said substantially solid conductive ground plane and electrically coupling said first conductive signal line to said second conductive signal line, said first and second conductive ground lines and said substantially conductive ground plane providing shielding for said at least one conductive signal line during the passage of electrical current through said signal line, said electrical component being electrically coupled to said printed circuit board.

23. (previously presented) The electrical assembly of claim 22 wherein said electrical component is a chip carrier.
24. (previously presented) The electrical assembly of claim 22 wherein said electrical component is a semiconductor chip.
25. (previously presented) The electrical assembly of claim 22 wherein said circuitized substrate further includes second and third conductive thru-holes, said second and third conductive thru-holes electrically coupling said first and second conductive ground lines to said substantially solid conductive ground plane.